

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,878,206 B2  
APPLICATION NO. : 10/016300  
DATED : April 12, 2005  
INVENTOR(S) : Tzu et al.

Page 1 of 4

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page should be deleted and substitute therefore the attached title page.

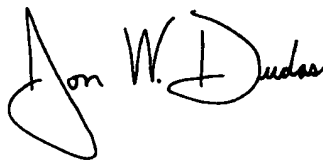
Drawings:

Delete drawing sheets 1-2, and substitute therefore the drawing sheets, consisting of Figs. 1-2, as shown on the attached pages.

Col. 5, line 59, insert a space (" ") after "20g."

Signed and Sealed this

Seventeenth Day of October, 2006

A handwritten signature in black ink, reading "Jon W. Dudas". The signature is stylized, with a large, looped initial "J" and a cursive "Dudas".

JON W. DUDAS  
*Director of the United States Patent and Trademark Office*

(12) **United States Patent**  
Tzu et al.

(10) Patent No.: **US 6,878,206 B2**  
(45) Date of Patent: **Apr. 12, 2005**

(54) **LID ASSEMBLY FOR A PROCESSING SYSTEM TO FACILITATE SEQUENTIAL DEPOSITION TECHNIQUES**

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(\*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 145 days.

(21) Appl. No.: 10/016,300

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(65) **Prior Publication Data**

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**Related U.S. Application Data**

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(52) U.S. Cl. 118/715; 118/728; 156/345.29; 156/345.33

(58) Field of Search 118/715, 728, 118/50; 156/345.29, 345.33, 345.34, 345.35, 345.36, 345.26, 345.51; 137/262, 263, 264, 454.2, 560, 561 R, 561 A, 571, 572, 573, 574, 575, 576, 590, 594-596, 599.01, 599.05-599.07, 602; 141/285, 286, 37, 44-47, 54, 301-302, 367

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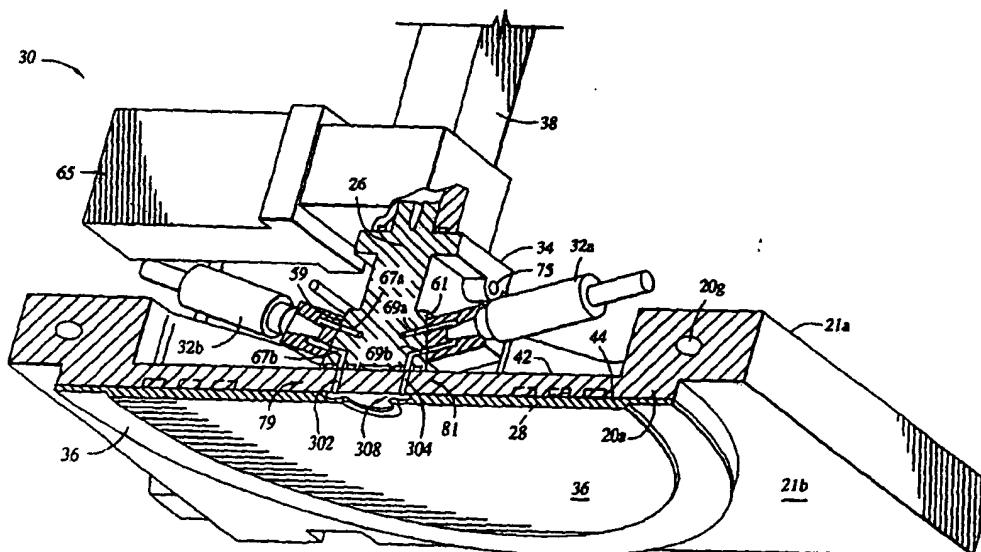
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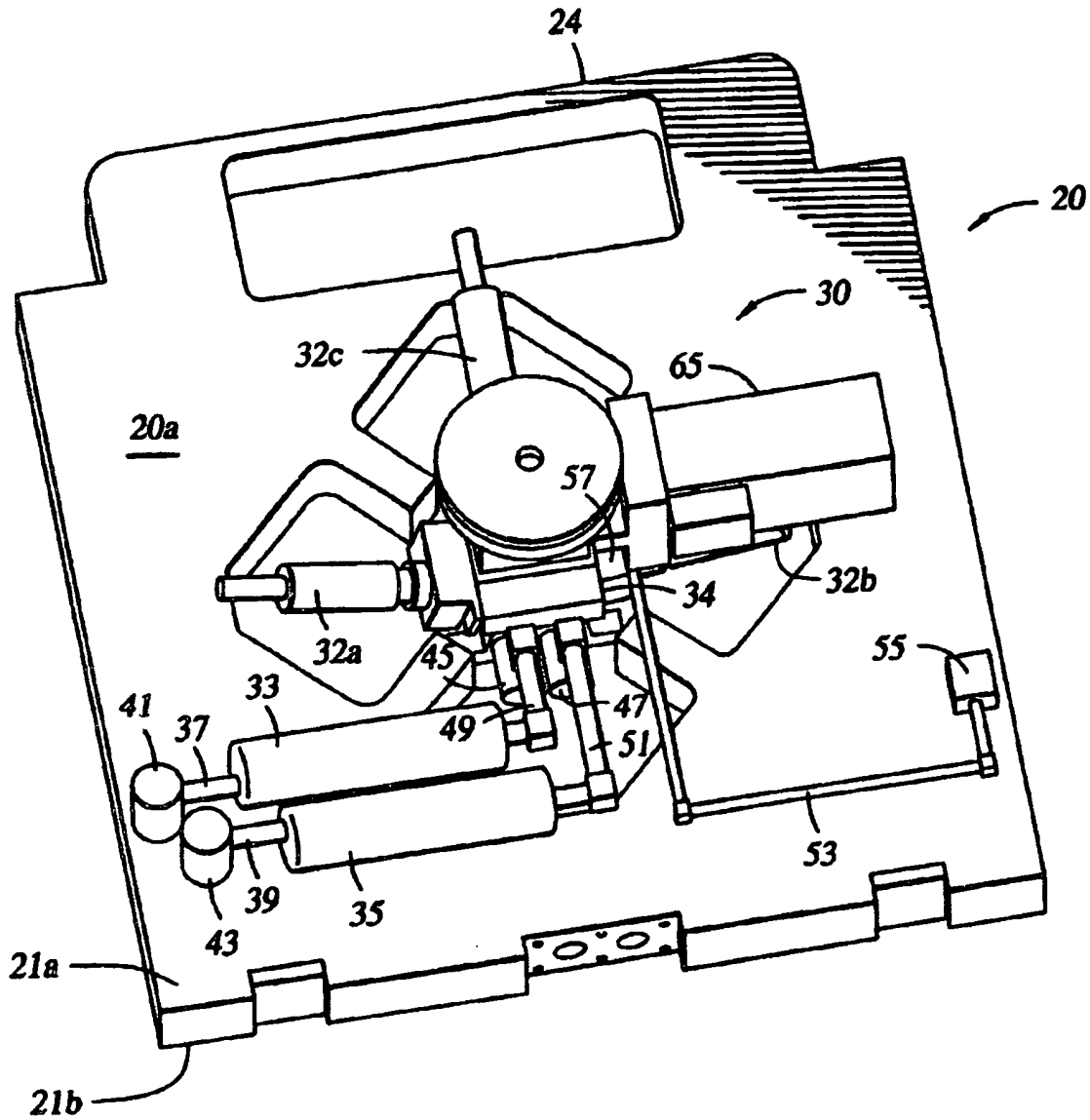
(57)

**ABSTRACT**

A lid assembly for a semiconductor processing system is provided. The lid assembly generally includes a lid having a gas manifold mounted on a first side and a baffle plate mounted on a second side. The gas manifold is configured to deliver a plurality of gases to a plenum defined between the baffle plate and the lid. The gases are mixed within a recess formed in the baffle plate before exiting into the processing system through a singular passage.

23 Claims, 8 Drawing Sheets



*Fig. 2*

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Fig. 3

